

ABSTRACT

The semiconductor processing pressure sensitive adhesive sheet of the present invention is a semiconductor processing pressure sensitive adhesive sheet including a substrate, an intermediate layer, and a pressure sensitive adhesive layer in this order, wherein the intermediate layer is a layer formed of an intermediate layer forming composition containing a non-energy ray-curable acrylic polymer (A) and an energy ray-curable acrylic polymer (B) having a weight average molecular weight of 50,000 to 250,000, the pressure sensitive adhesive layer is energy ray-curable, and a difference in elastic modulus at 23°C between the intermediate layer and the pressure sensitive adhesive layer after energy ray curing is 20 MPa or less.